# SPECIFICATIONS FOR NICHIA CHIP TYPE **BLUE** LED

 $\mathsf{MODEL}: NHSB046T$ 

NICHIA CORPORATION

#### 1.SPECIFICATIONS

(1) Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$ 

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	10	mA
Pulse Forward Current	IFP	30	mA
Allowable Reverse Current	Ir	85	mA
Power Dissipation	PD	30	mW
Operating Temperature	Topr	<b>-40</b> ∼ +100	°C
Storage Temperature	Tstg	<b>-40</b> ∼ +100	°C
Soldering Temperature	Tsld	Reflow Soldering: 260°C f	or 10sec.
		Dip Soldering : 260°C f	or 10sec.
		Hand Soldering : 350°C f	for 3sec.

IFP Conditions : Pulse Width  $\leq 10$ msec. and Duty  $\leq 1/10$ 

(2) Initial Electrical/Optical Characteristics

 $(Ta=25^{\circ}C)$ 

initial Electrical Sprical Characteristics						u 23 C)
Item		Symbol	Condition	Тур.	Max.	Unit
Forward Voltage		VF	$I_F=5[mA]$	(2.9)	3.1	V
Luminous Intensity		Iv	I <sub>F</sub> =5[mA]	(31)	-	mcd
* Characticitae Consultinate	X	-	I <sub>F</sub> =5[mA]	0.133	-	-
Chromaticity Coordinate	у	-	I <sub>F</sub> =5[mA]	0.075	-	-

<sup>\*</sup> Please refer to CIE 1931 chromaticity diagram.

(3) Ranking

 $(Ta=25^{\circ}C)$ 

Item	Symbol	Condition	Min.	Max.	Unit	
	Rank S	Iv	I <sub>F</sub> =5[mA]	37	52	mcd
Luminous Intensity	Rank R	Iv	I <sub>F</sub> =5[mA]	26	37	mcd
	Rank Q	Iv	I <sub>F</sub> =5[mA]	19	26	mcd

<sup>\*</sup> Luminous Intensity Measurement allowance is  $\pm$  10%.

Color Ranks

 $(I_F=5mA,T_a=25^{\circ}C)$ 

	Rank W1							
X	0.137	0.124	0.142	0.151				
y	0.037	0.058	0.081	0.058				

	Rank W2						
X	0.124	0.110	0.132	0.142			
у	0.058	0.087	0.112	0.081			

<sup>\*</sup> Color Coordinates Measurement allowance is  $\pm 0.01$ .

# 2.TYPICAL INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS

Please refer to figure's page.

<sup>\*</sup> One delivery will include up to two color ranks and three luminous intensity ranks of the products.

The quantity-ratio of the ranks is decided by Nichia.

#### 3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

Material as follows; Package : Heat-Resistant Polymer

Encapsulating Resin : Epoxy Resin (with Diffused)
Electrodes : Ag Plating Copper Alloy

#### 4.PACKAGING

· The LEDs are packed in cardboard boxes after taping.

Please refer to figure's page.

The label on the minimum packing unit shows; Part Number, Lot Number, Ranking, Quantity

- · In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
- The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- · The boxes are not water resistant and therefore must be kept away from water and moisture.
- · When the LEDs are transported, we recommend that you use the same packing method as Nichia.

#### 5.LOT NUMBER

The first six digits number shows **lot number**.

The lot number is composed of the following characters;

 $\bigcirc \square \times \times \times \times - \triangle \blacksquare$ 

O - Year (4 for 2004, 5 for 2005)

☐ - Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)

×××× - Nichia's Product Number

 $\triangle$  - Ranking by Color Coordinates

Ranking by Luminous Intensity

## **6.RELIABILITY**

## (1) TEST ITEMS AND RESULTS

) TEST HEMS AND RES		1	<u> </u>	T
	Standard			Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance to	JEITA ED-4701	Tsld=260°C, 10sec.	1 time	0/22
Soldering Heat	300 301	(Pre treatment 30°C,70%,168hrs.)		
(Dip Soldering)	IDITA ED 4701	T-11-225   50C 2	1 4	0/22
Solderability (Din Soldering)	JEITA ED-4701	Tsld= $235 \pm 5^{\circ}$ C, 2sec.	1 time	0/22
(Dip Soldering)	300 303	(using flux) Tsld=260°C, 10sec.	over 95%	0/22
Resistance to	JEITA ED-4701	· · · · · · · · · · · · · · · · · · ·	2 times	0/22
Soldering Heat	300 301	(Pre treatment 30°C,70%,168hrs.)		
(Reflow Soldering)	IDITA ED 4701	T-11-215 + 50C 2	1 time	0/22
Solderability (Reflect Soldering)	JEITA ED-4701 300 303	Tsld=215 ± 5°C, 3sec.		0/22
(Reflow Soldering)		(using flux, Lead Solder)	over 95%	0.44.0.0
Thermal Shock	JEITA ED-4701	-40°C ~ 100°C	100 cycles	0/100
	300 307	1min. (10sec.) 1min.		
	TETEL ED 1501	(Pre treatment 30°C,70%,168hrs.)	100 1	0.44.0.0
Temperature Cycle	JEITA ED-4701	-40°C ~ 25°C ~ 100°C ~ 25°C	100 cycles	0/100
	100 105	30min. 5min. 30min. 5min.		
Moisture Resistance Cyclic	JEITA ED-4701	25°C ~ 65°C ~ -10°C	10 cycles	0/100
	200 203	90%RH 24hrs./1cycle		
High Temperature Storage	JEITA ED-4701	Ta=100°C	1000 hrs.	0/100
	200 201			
Temperature Humidity	JEITA ED-4701	Ta=60°C, RH=90%	1000 hrs.	0/100
Storage	100 103			
Low Temperature Storage	JEITA ED-4701	Ta=-40°C	1000 hrs.	0/100
	200 202			
Steady State Operating Life		Ta=25°C, IF=10mA	1000 hrs.	0/100
**				
Steady State Operating Life		Ta=85°C, IF=5mA	1000 hrs.	0/100
of High Temperature ★★				
Steady State Operating Life		60°C, RH=90%, IF=5mA	1000 hrs.	0/100
of High Humidity Heat **				
Steady State Operating Life		Ta=-40°C, IF=5mA	1000 hrs.	0/100
of Low Temperature **		,		
Permanence of Marking	JEITA ED-4701	Solvent : Isopropyl Alcohol	1 time	0/22
1 cilianence of iviarking	500 501	Solvent Temperature : 20 ~ 25°C	1 time	0/22
	000001	Dipping Time : 5 min.		
Vibration	JEITA ED-4701	$200 \text{m/s}^2$ , $100 \sim 2000 \text{Hz}$ (Sweep 4min.)	4 times	0/10
. 1014011	400 403	48min., 3directions		3/10
Drop	.00 102	75cm	3 times	0/10
Electrostatic Discharge	JEITA ED-4701	R=1.5kΩ, C=100pF	3 times	0/22
Discharge	300 304	Test Voltage=2kV	Negative/Positive	0,22

# (2) CRITERIA FOR JUDGING THE DAMAGE

Criteria for Judgament							
_			Criteria for Judgement				
Item	Symbol	Test Conditions	Min.	Max.			
Forward Voltage	VF	IF=5mA	-	U.S.L.*)× 1.1			
Luminous Intensity Condition 1	Iv	IF=5mA	L.S.L.**)× 0.7	-			
Luminous Intensity Condition 2 **	Iv	I <sub>F</sub> =5mA	L.S.L.**)× 0.5	-			

<sup>\*)</sup> U.S.L. : Upper Standard Level

<sup>\*\*)</sup> L.S.L.: Lower Standard Level

<sup>\*\*</sup> These test items are judged by the criteria of Luminous Intensity Condition 2.

#### 7.CAUTIONS

#### (1) Moisture Proof Package

- · When moisture is absorbed into the SMT package it may vaporize and expand during soldering. There is a possibility that this can cause exfoliation of the contacts and damage to the optical characteristics of the LEDs. For this reason, the moisture proof package is used to keep moisture to a minimum in the package.
- The moisture proof package is made of an aluminum moisture proof bag with a zipper. A package of a moisture absorbent material (silica gel) is inserted into the aluminum moisture proof bag. The silica gel changes its color from blue to pink as it absorbs moisture.

#### (2) Storage

· Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

#### After opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

· If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : more than 24 hours at  $65 \pm 5$ °C

- · Nichia LED electrode sections are comprised of a silver plated copper alloy. The silver surface may be affected by environments which contain corrosive gases and so on. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the User use the LEDs as soon as possible.
- · Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

#### (3) Heat Generation

- Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.
- · The operating current should be decided after considering the ambient maximum temperature of LEDs.

#### (4) Soldering Conditions

• The LEDs can be soldered in place using the reflow soldering method and the dip soldering method.

· Recommended soldering conditions

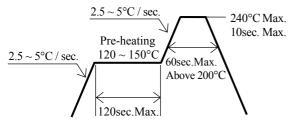
	Reflow Solderin	g	Dip Sol	dering	Hand So	oldering
	Lead Solder	Lead-free Solder				
Pre-heat	120 ∼ 150°C	180 ~ 200°C	Pre-heat	100°C Max.	Temperature	350°C Max.
Pre-heat time	120 sec. Max.	120 sec. Max.	Pre-heat time	60 sec. Max.	Soldering time	3 sec. Max.
Peak	240°C Max.	260°C Max.	Solder bath	260°C Max.		(one time only)
temperature			temperature			
Soldering time	10 sec. Max.	10 sec. Max.	Dipping time	10 sec. Max.		
Condition	refer to	refer to				
	Temperature	Temperature				
	- profile ①.	- profile ②.				
		$(N_2 \text{ reflow is})$				
		recommended.)				

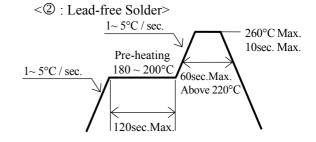
\* After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

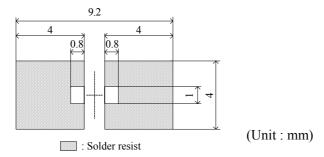
<1 : Lead Solder>





[Recommended soldering pad design]

Use the following conditions shown in the figure.



- · Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- · Reflow soldering should not be done more than two times.
- · When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.

#### (5) Cleaning

- · It is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.
- · Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

#### (6) Static Electricity

- · Static electricity or surge voltage damages the LEDs.

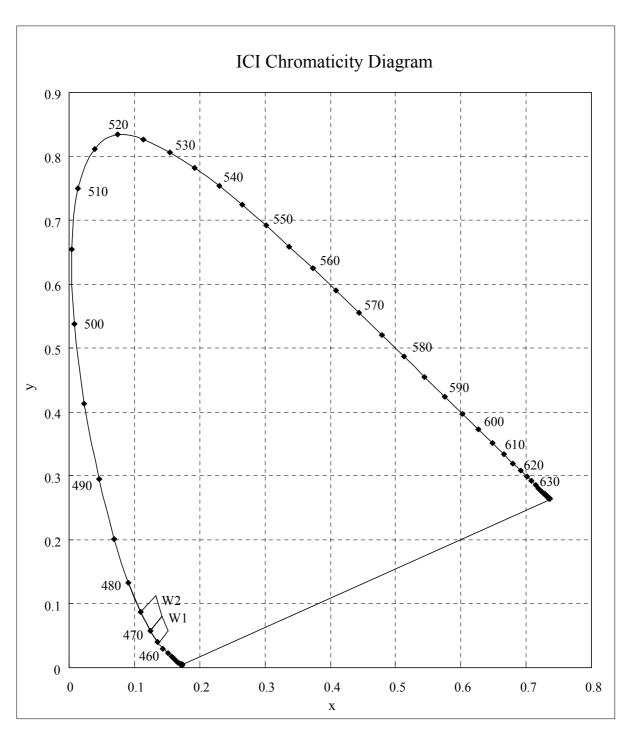
  It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- · All devices, equipment and machinery must be properly grounded.

  It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs.
- · When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended).
- · Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current.

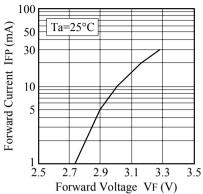
Criteria: (VF > 2.0V at IF=0.5mA)

#### (7) Others

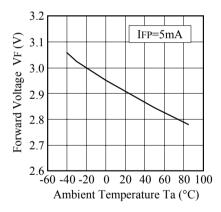
- The LED light output is strong enough to injure human eyes. Precautions must be taken to prevent looking directly at the LEDs with unaided eyes for more than a few seconds.
- · Flashing lights have been known to cause discomfort in people; you can prevent this by taking precautions during use. Also, people should be cautious when using equipment that has had LEDs incorporated into it.
- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
- · User shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the User shall inform Nichia directly before disassembling or analysis.
- The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
- The appearance and specifications of the product may be modified for improvement without notice.



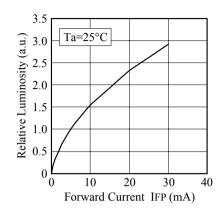
\* Color Coordinates Measurement allowance is  $\pm 0.01$ .



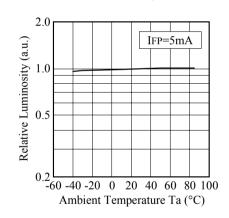
■ Ambient Temperature vs. Forward Voltage



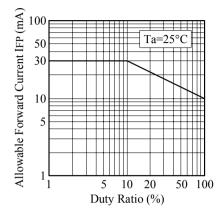
■ Forward Current vs. Relative Luminosity



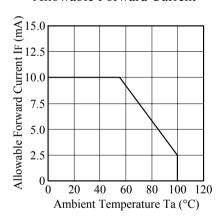
■ Ambient Temperature vs. Relative Luminosity



Duty Ratio vs.Allowable Forward Current

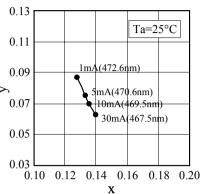


■ Ambient Temperature vs. Allowable Forward Current



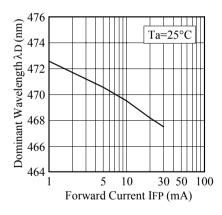
NICHIA CORPORATION

	Model	NHSB046	
1	Title	CHARACTERISTICS	
	No.	050221537421	

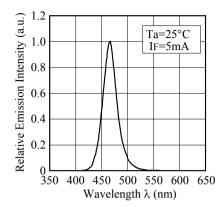


■ Forward Current vs.

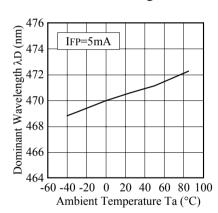
Dominant Wavelength



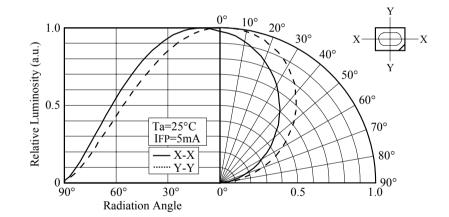
■ Spectrum



■ Ambient Temperature vs. Dominant Wavelength



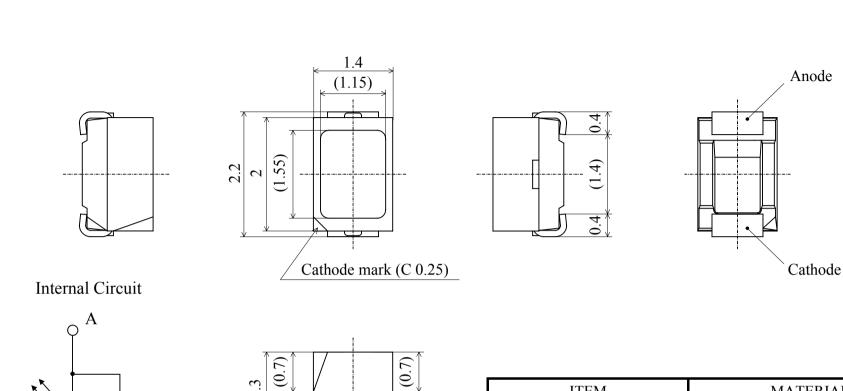
■ Directivity



NICHIA CORPORATION

	Model	NHSB046	
1	Title	CHARACTERISTICS	
	No.	050221537431	

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0.9

Protection device

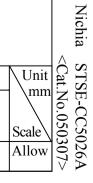
K

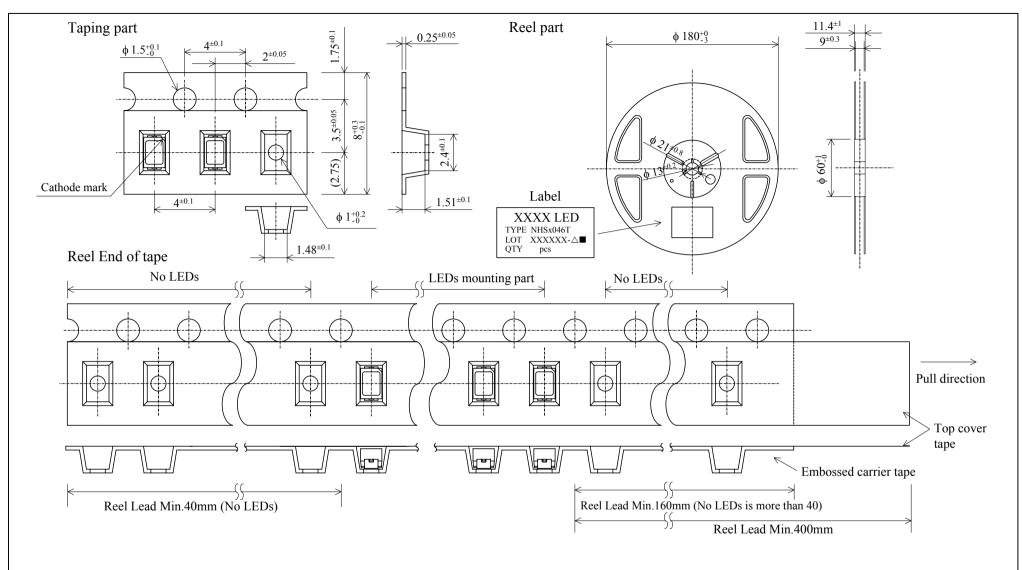
ITEM	MATERIALS
PACKAGE	Heat-Resistant Polymer
ENCAPSULATING RESIN	Epoxy Resin (with Diffused)
ELECTRODES	Ag Plating Copper Alloy

Nichia

\* NHSB046 has a protection device built in as a protection circuit against static electricity.

	Model	NHSB046	Unit Cat.
NICHIA CORPORATION	Title	OUTLINE DIMENSIONS	15/1 No.050 Scale Scale
	No.	050208537031	Allow ±0.1





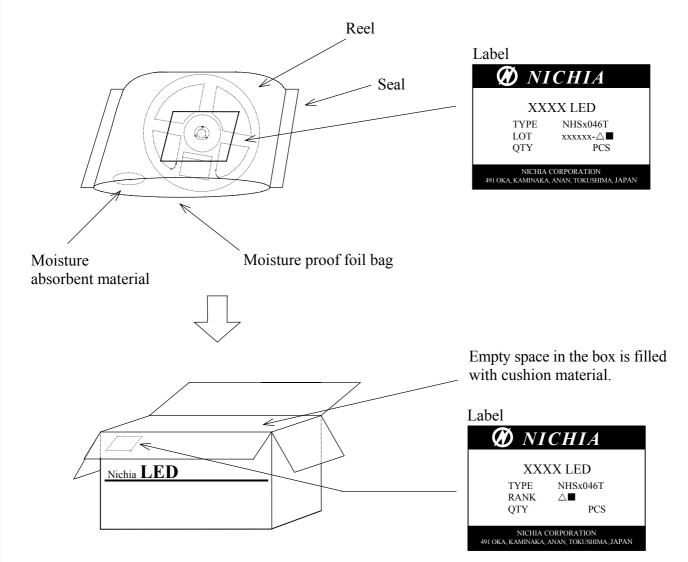
3,000pcs/Reel

Taping is based on the  $JIS\ C\ 0806$  : Packaging of Electronic

Components on Continuous Tapes.

	Model	NHSx046T	Unit	1 ?
NICHIA CORPORATION	Title	TAPING DIMENSIONS	Scale	
	No.	050128537051	Allow	1

The reel and moisture absorbent material are put in the moisture proof foil bag and then heat sealed.



Packing unit

	Reel/bag	Quantity/bag (pcs)
Moisture proof foil bag	1reel	3,000 MAX.

Cardboard box	Dimensions (mm)	Reel/box	Quantity/box (pcs)
Cardboard box S	$270\times280\times100\times4t$	4reel MAX.	12,000 MAX.
Cardboard box M	270×280×200×4t	10reel MAX.	30,000 MAX.
Cardboard box L	270×280×300×4t	16reel MAX.	48,000 MAX.

	Model	NHSx046T	
NICHIA CORPORATION	Title	PACKING	
	No.	050128537071	